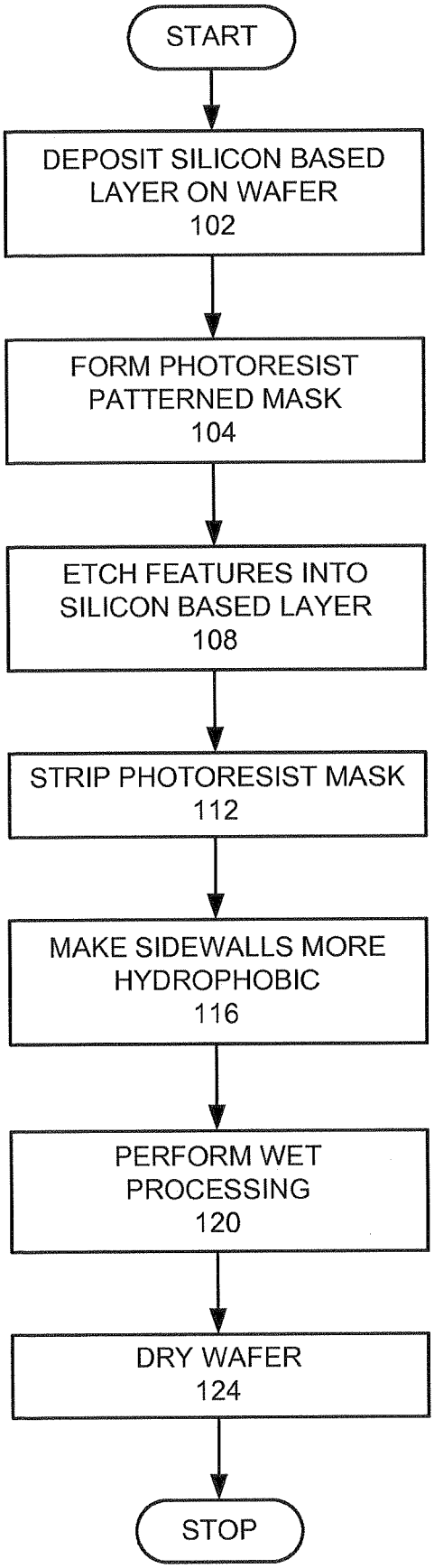

START
DEPOSIT SILICON BASED LAYER ON WAFER 102
FORM PHOTORESIST PATTERNED MASK 104
ETCH FEATURES INTO SILICON BASED LAYER 108
STRIP PHOTORESIST MASK 112
MAKE SIDEWALLS MORE HYDROPHOBIC 116
PERFORM WET PROCESSING 120
DRY WAFER 124
STOP

FIG. 1A

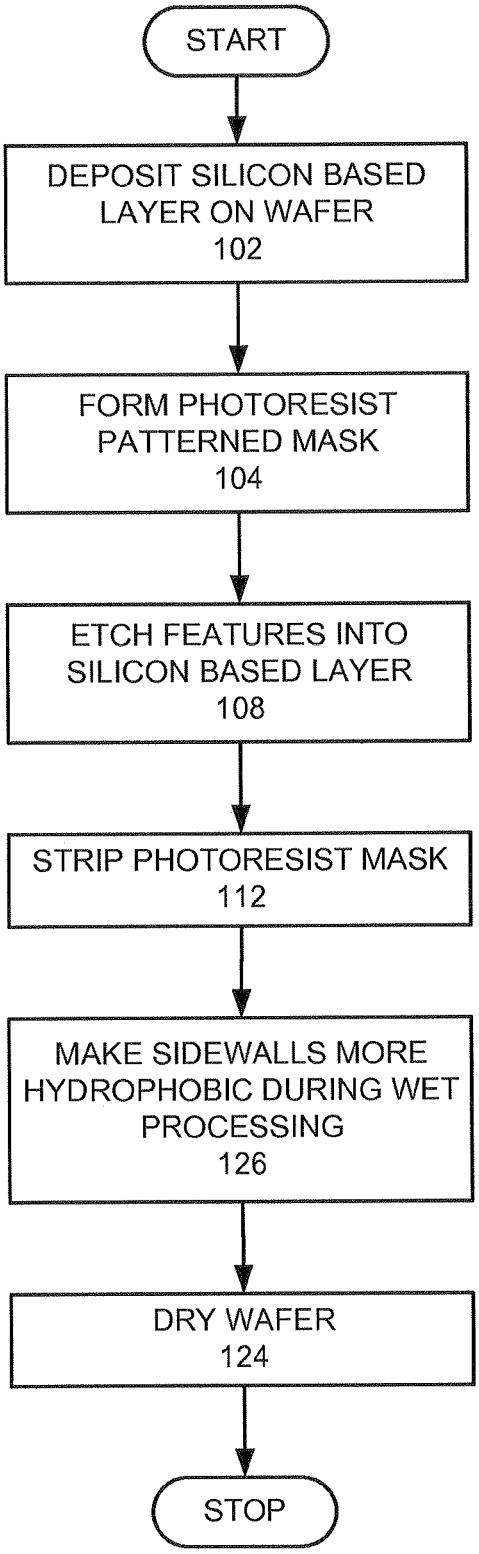

START
DEPOSIT SILICON BASED LAYER ON WAFER 102
FORM PHOTORESIST PATTERNED MASK 104
ETCH FEATURES INTO SILICON BASED LAYER 108
STRIP PHOTORESIST MASK 112
MAKE SIDEWALLS MORE HYDROPHOBIC DURING WET PROCESSING 126
DRY WAFER 124
STOP

FIG. 1B

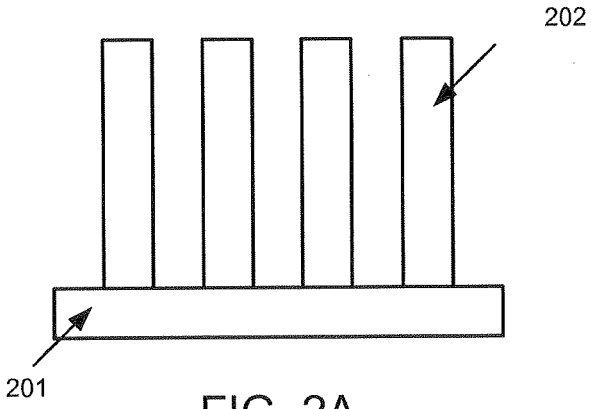


FIG. 2A

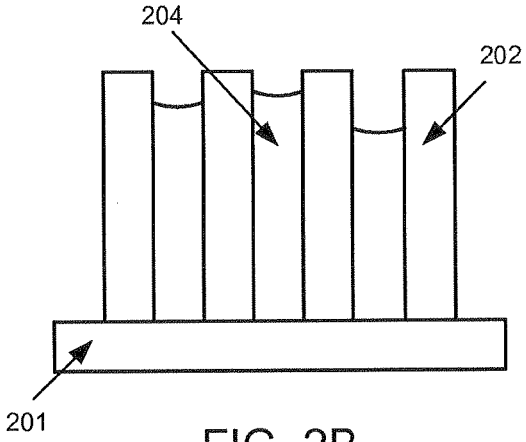


FIG. 2B

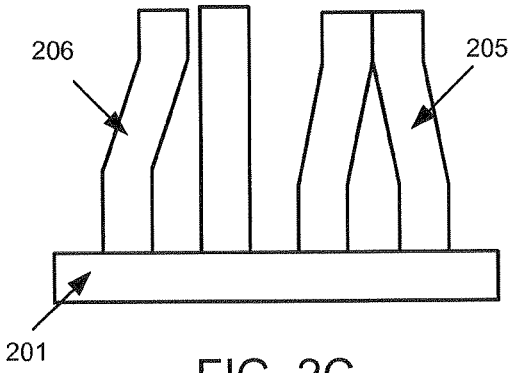


FIG. 2C

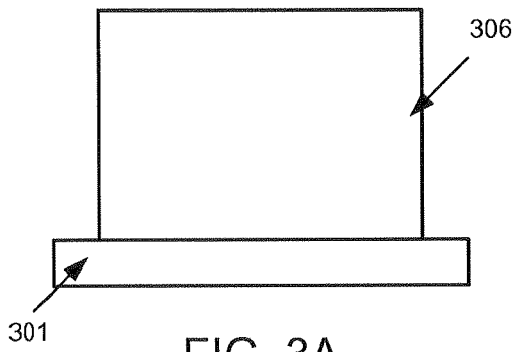


FIG. 3A

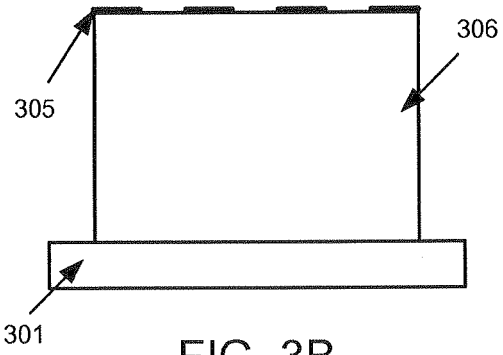


FIG. 3B

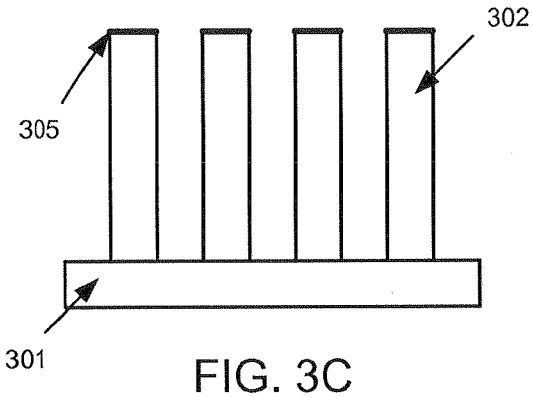


FIG. 3C

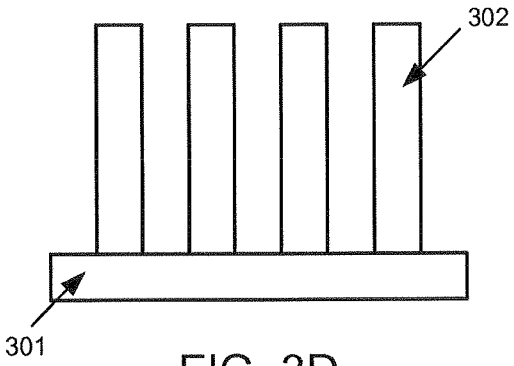


FIG. 3D

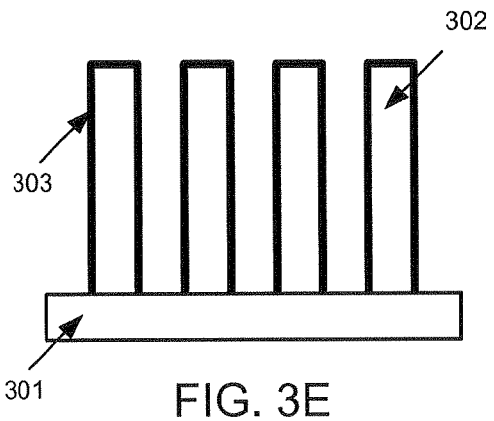


FIG. 3E

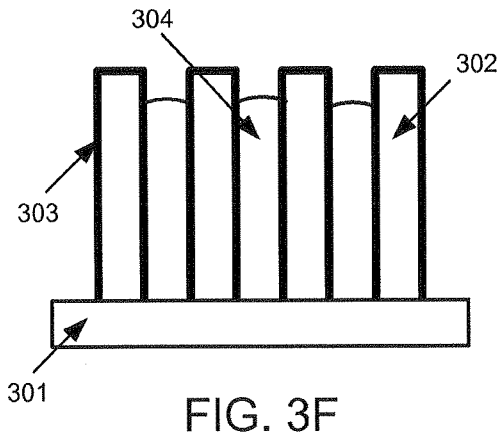


FIG. 3F

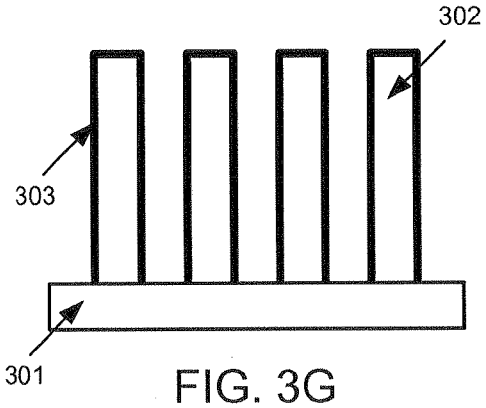


FIG. 3G

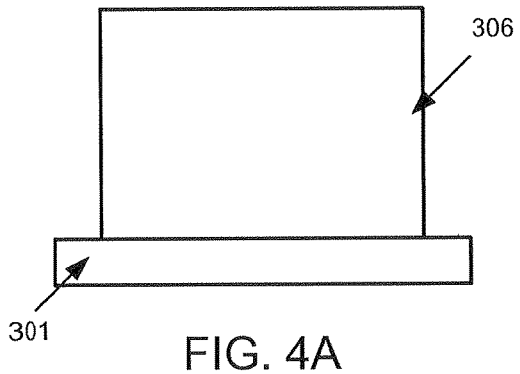


FIG. 4A

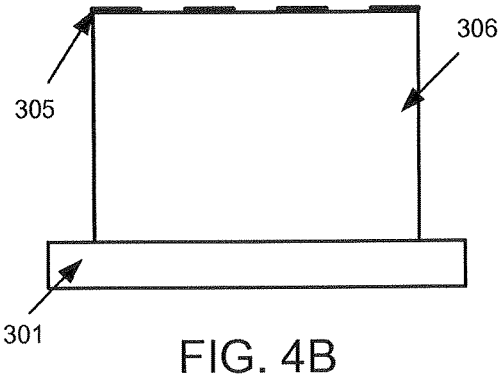


FIG. 4B

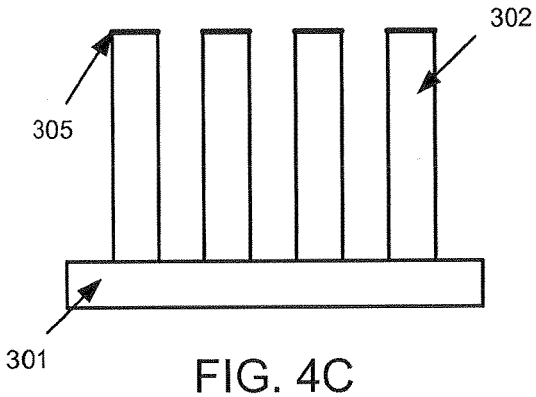


FIG. 4C

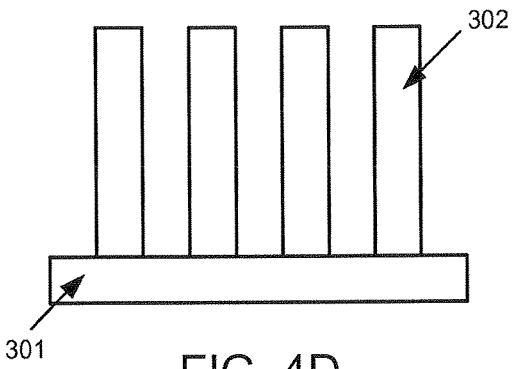


FIG. 4D

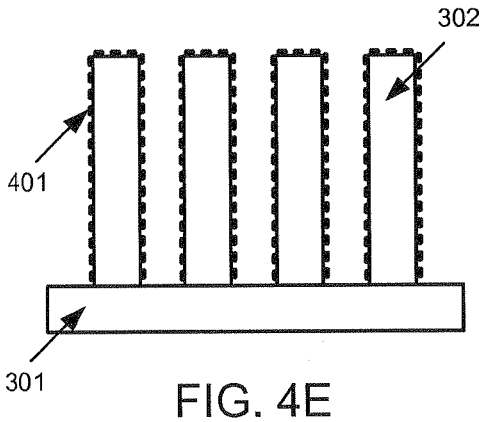


FIG. 4E

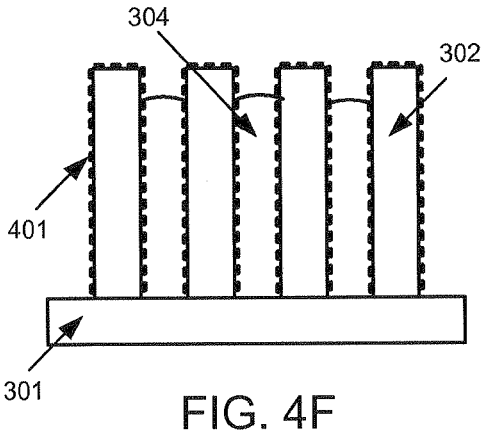


FIG. 4F

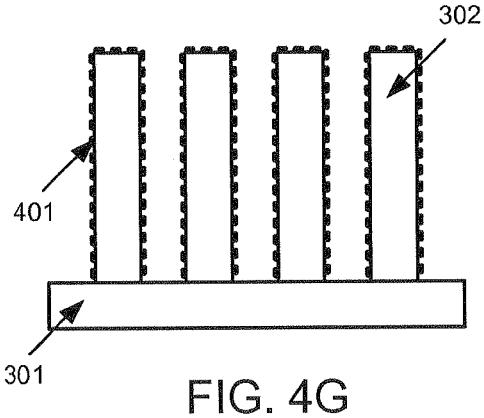


FIG. 4G

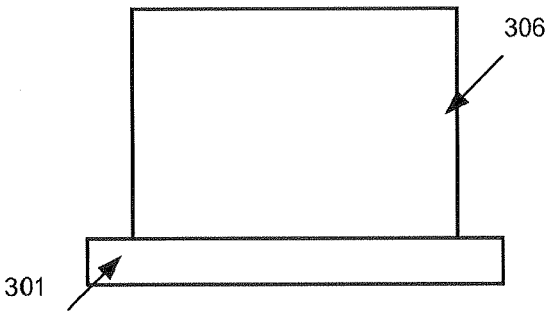


FIG. 5A

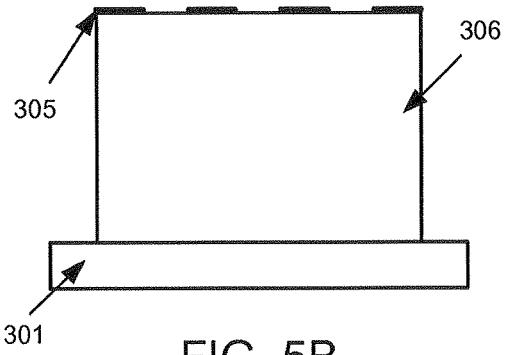


FIG. 5B

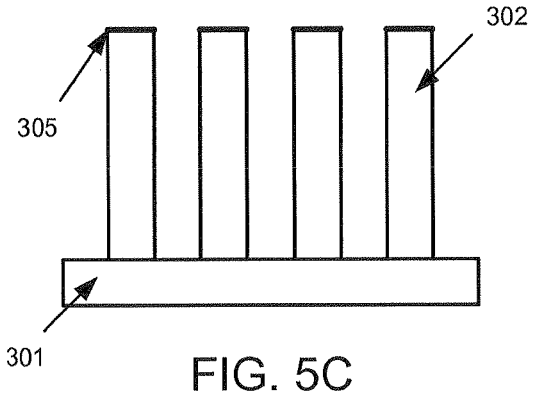


FIG. 5C

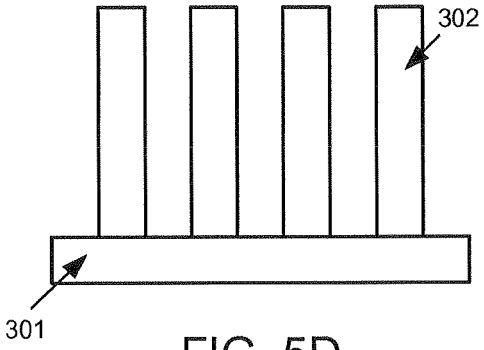


FIG. 5D

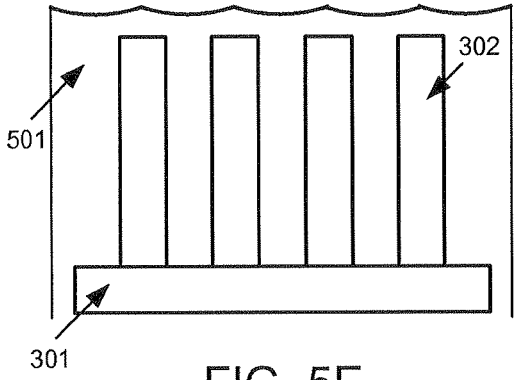


FIG. 5E

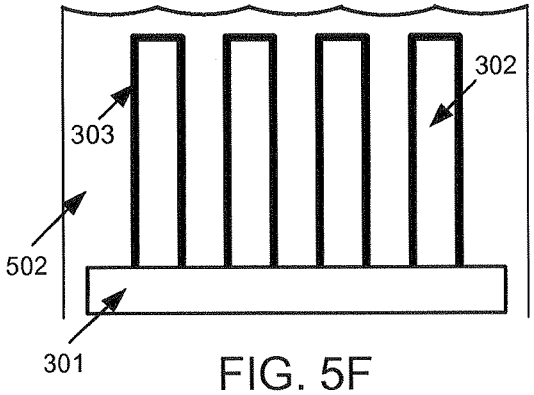


FIG. 5F

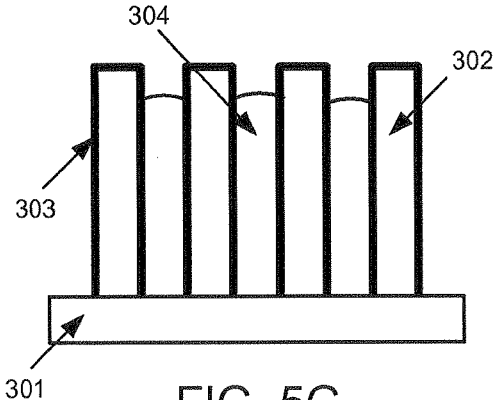


FIG. 5G

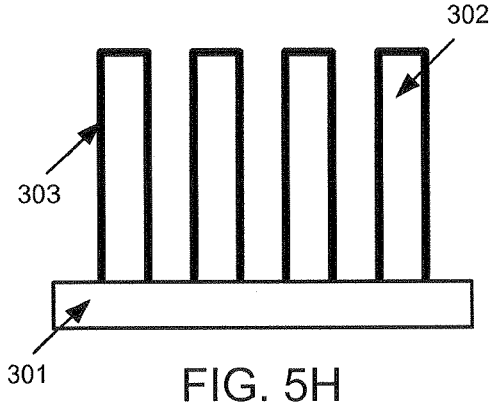


FIG. 5H